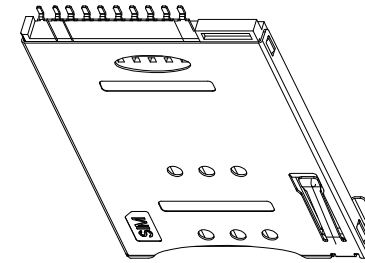
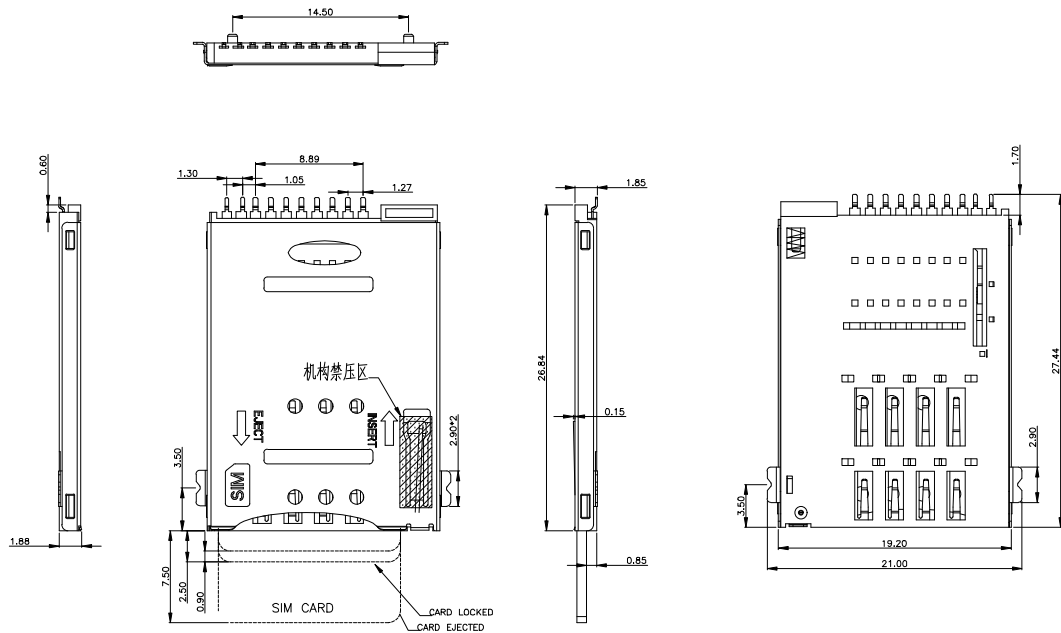
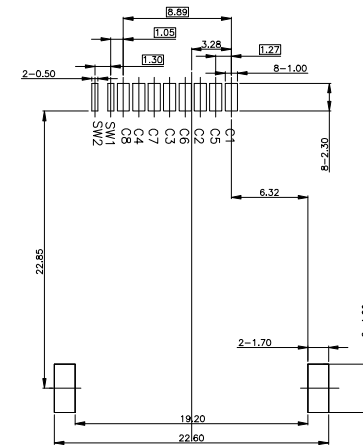




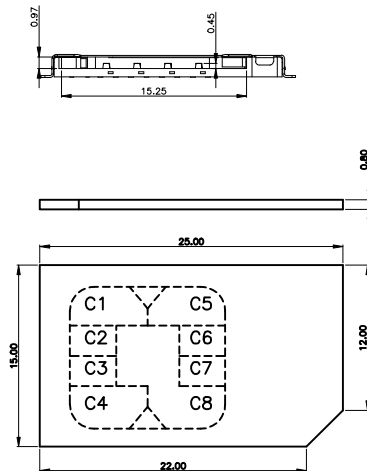
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



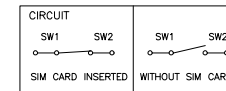
pin no.	name
C1	vcc of sim
C2	rst of sim
C3	clk of sim
C5	gnd of sim
C6	vpp of sim
C7	I/O of sim
C4/C8	n/a
SW1	switch1
SW2	switch2



RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



SPECIFICATION
MATERIAL:
 INSULATOR: HIGH TEMPERATURE THERMOPLASTIC,
 UL 94V-0.COLOR"BLACK LCP
 CONTACT: COPPER ALLOY
PLATING:
 CONTACT: PLATED 30U" NI OVERALL
 PLATED AU SELECTIVE CONTACT AREA
 SHELL: PLATED 30U" NI OVERALL,PAD G/F AU
ELECTRICAL:
 CURRENT RATING: 0.5AMPS
 VOLTAGE RATING: 5V AC/DC
 AMBIENT TEMPERATURE RANGE: -20°C~+60°C
 STORAGE TEMPERATURE RANGE: -40°C~+80°C
 AMBIENT HUMIDITY RANGE: 95% R.H. MAX.
 CONTACT RESISTANCE: 100MΩMAX.
 INSULATION RESISTANCE: 1000MΩMIN./500VDC
 MATING CYCLES: 5,000 INSERTIONS
 REFLOW PEAK TEMP: 260°C



UNLESS OTHERWISE
SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.5	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.10	



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	Mini Sim Card Push Push 8+2P Smt无铅		
DWN	xiong	SIM-206	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1
			REV: A4

CUSTOMER COPY